



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN200804

Date: February 24, 2020

Subject: Qualification of Fab 25 as an Additional Wafer Fab Site, Cu Wire, EME-G660B Mold Compound and Marketing Part Number Change for Select MM MCU Products

Change Type: Major

Description of Change:

Cypress announces the qualification of Fab 25 (5204 East Ben White Boulevard, Austin, TX 78741, USA) as an additional wafer fab site for select Mass Market (MM) MCU products. The current products are fabricated at ON Semiconductor Aizu Co., Ltd (OSA, No.6 Kogyo Danchi, Monden-Machi, Aizu Wakamatsu, Fukushima, 965-8506, Japan). Cypress also announces that the wire and package mold material is changing to the standard J-Devices Cu-wire and EME-G660B mold compound. In addition, the part number is changing from a MB prefix to a CY prefix, including a marking change of “F-logo” or “Spansion logo” removal.

Changes	Current	New
Wafer Fab Site	ON Semiconductor Aizu Co., Ltd, Japan	Fab 25, USA
Wire	Au-wire	Cu-wire
Mold Compound	Hitachi Epoxy CEL-9210H	Sumitomo Epoxy EME-G660B
Part Number	MB***	CY***
Logo Marking	F-logo or Spansion logo	No logo

Benefit of Change:

Qualification of alternate manufacturing sites are part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

Part Numbers Affected: 1

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

The product has been qualified through a series of tests documented in the Qualification Test Plans summarized in the table below. These qualification reports can be found as attachments to this PCN or by visiting www.cypress.com and typing the QTP number in the keyword search window.

QTP Number	Qualification
172101	8/16/32-bit Microcontrollers, 350nm Technology (CU60F), FAB 25
	LQFP Package, Lead-Free, Cu Wire (CuPdAu), EME-G600B, JD Usuki

Sample Status:

Qualification samples may not be built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated Fab 25 sample ordering part numbers. Sample ordering part numbers are subject to lead times. If you require qualification samples, please contact your local Cypress Sales Representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

Effective 90 days from the date of this notification, all shipments of the affected part number in the attached file will be fabricated at either Fab 25 or other qualified wafer fabrication sites.

Anticipated Impact:

Products fabricated at the new site are completely compatible with existing products from form, fit, functional, parametric and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item	Marketing Part Number	Sample/Replacement Ordering Part Number	Sample Availability	Last Time Buy Date	Last Time Ship Date
1	MB90F823BPMC1-GE1	CY90F823BPMC1-G-UJE1	31-Jan-20	31-Mar-20	30-Sep-20